



1.27µm MIN.	0.9µm MIN.	0.76µm MIN.	5011935100	バラ状 LOOSE
1.0µm MIN.		0.38µm MIN.	5011935000	連鎖状 CHAIN
		0.1µm MIN.	5011936100	バラ状 LOOSE
			5011936000	連鎖状 CHAIN
			5011933100	バラ状 LOOSE
			5011933000	連鎖状 CHAIN
下地: ニッケルめっき UNDER PLATING: NICKEL PLATING	バレル外側: 錫めっき OUTSIDE OF BARREL: TIN PLATING	接点部: 金めっき CONTACT AREA: GOLD PLATING	オーダー番号 ORDER NO.	端子形状 FORM
めっき仕様(前めっき): PLATING(PRE-PLATING)				

<b>MATERIAL</b> りん青銅 下地ニッケル、部分金めっき、錫めっき品 PHOSPHOR BRONZE t=0.12 SELECTIVE GOLD PLATING、SELECTIVE TIN PLATING、 UNDER NICKEL PLATING
<b>FINISH</b> SEE NOTE
<b>WIRE RANGE</b> AWG#28-32
<b>INS. RANGE</b> ∅0.4-0.8

REDRAWN AND REVISED EC NO: 168346 DRWN: KYAMADA02 CHK'D: SAKIYAMA APPR: TKANEKO	2017/09/28	2017/11/30	2017/12/01
	GENERAL TOLERANCES (UNLESS SPECIFIED)		
	4 PLACES	± 0.2	
	3 PLACES	± 0.2	
	2 PLACES	± 0.2	
	1 PLACE	± 0.2	
	0 PLACES	± 0.2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

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DIMENSION UNITS mm		SCALE 20:1	
DRWN BY QHE31		DATE 2017/04/03	
CHK'D BY SAKIYAMA		DATE 2017/04/06	
APPR BY TKANEKO		DATE 2017/04/06	
DRAWING SIZE A3		THIRD ANGLE PROJECTION	
<b>molex®</b>			
PICO-CLASP 1.0 W/B CONN CRIMP REC TERM (GOLD PLATING)			
PRODUCT CUSTOMER DRAWING			
SERIES 501193	MATERIAL NUMBER SEEB TABLE	CUSTOMER	
DOCUMENT NUMBER 5011930000		DOC TYPE PSD	DOC PART 000
		SHEET NUMBER 1 OF 1	